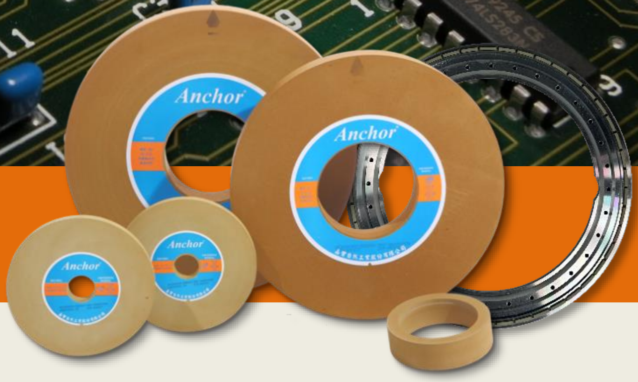
Anchor®

HSP®

Heterogeneous Surface Polishing

Applied in IC Board, PLP, FOPLP



Efficient, Non-stick
Better roughness

IC board could be divided into ABF, BT and MIS by the materials and process. Part of the process is based on epoxy resin as the main sealing film material, and with the copper wires which are electroplated to build on each molding layer (the figure shown as below). Therefore, the grinding wheel will simultaneously grind both epoxy resin and copper wires in the grinding process.

In addition to the grinding process of the above-mentioned substrate manufacturing. HSP wheel also provides the best solutions for the application grinding process of EMC packaging (Epoxy Molding Compounds), PLP panel level packaging, FOPLP, and functional plastic materials such as PEEK (polyetheretherketone) and PPS (polyphenylene sulfide) grinding.

Current processing experience includes : Pure cooper, Cooper + EMC, ABF + cooper, BT + cooper, EMC + Chip, Invar, PEEK, PPS and so on.

Wheel specification of HSP

Grit size		Wheel size	Machine
#320 #600 #800 #1000	#1200 #1500 #2000 #3000	6”- 20” Peripheral grinding	Horizontal spindle surface grinder
		6”- 20” Backside grinding	Vertical spindle backside grinder

■ Wheel size could be customized by the machine type.

Case study of HSP applied on IC board

Wheel type	HSP
Machine	Horizontal spindle surface grinder
Application	IC board with higher cooper content **(Cu>50%)**
Material	Cooper + EMC
Result	Lower loading, improved yield, good roughness, Ra < 0.3um

Specification HSP

Wheel size(mm) 355x75x127

Wheel speed 30-32 m/s

Feed rate 30 m/min

Depth setting (rough) 7um (middle) 4um (finish) 2um

COMPANY INFORMATION

Carbo Tzujan Industrial Co., Ltd.

For details, please contact the following agency.

MIRDC
ISO 9001 45001 14001

Contact us:
- TEL : +8862-2679-3461 #132
- FAX : +8862-8677-1742
- Address : No1, Fu An St, Yingge Dist, New Taipei City, Taiwan

Online service :
Website : www.carbo.com.tw
E-mail : webmaster@carbo.com.tw

■ While using grinding wheels, its essential that observing correct procedures.